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# LM35 Precision Centigrade Temperature Sensors

Technical

Documents

### **1** Features

- Calibrated Directly in Celsius (Centigrade)
- Linear + 10-mV/°C Scale Factor
- 0.5°C Ensured Accuracy (at 25°C)
- Rated for Full –55°C to 150°C Range
- Suitable for Remote Applications
- Low-Cost Due to Wafer-Level Trimming
- Operates from 4 V to 30 V
- Less than 60-μA Current Drain
- · Low Self-Heating, 0.08°C in Still Air
- Non-Linearity Only ±¼°C Typical
- Low-Impedance Output, 0.1  $\Omega$  for 1-mA Load

## 2 Applications

- · Power Supplies
- Battery Management
- HVAC
- Appliances

### 3 Description

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Software

The LM35 series are precision integrated-circuit temperature devices with an output voltage linearlyproportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of ±1/4°C at room temperature and ±3/4°C over a full -55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low-output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60  $\mu$ A from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a -55°C to 150°C temperature range, while the LM35C device is rated for a -40°C to 110°C range (-10° with improved accuracy). The LM35-series devices are available packaged in hermetic TO transistor packages, while the LM35C, LM35CA, and LM35D devices are available in the plastic TO-92 transistor package. The LM35D device is available in an 8-lead surface-mount small-outline package and a plastic TO-220 package.

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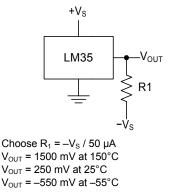
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Device mornation								
PART NUMBER	PACKAGE	BODY SIZE (NOM)						
	TO-CAN (3)	4.699 mm × 4.699 mm						
1 M25	TO-92 (3)	4.30 mm × 4.30 mm						
LM35	SOIC (8)	4.90 mm × 3.91 mm						
	TO-220 (3)	14.986 mm × 10.16 mm						

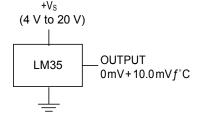
Device Information<sup>(1)</sup>

(1) For all available packages, see the orderable addendum at the end of the datasheet.

#### Full-Range Centigrade Temperature Sensor



### Basic Centigrade Temperature Sensor (2°C to 150°C)



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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Easture Description

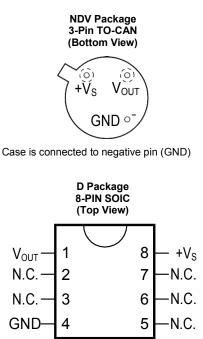
# 4 Revision History

anges from Revision F (January 2016) to Revision G	Page
Equation 1, changed From: 10 mV/°F To: 10mv/°C Power Supply Recommendations, changed From: "4-V to 5.5-V power supply" To: "4-V to 30-V power supply:	
anges from Revision E (January 2015) to Revision F	Page
Changed NDV Package (TO-CAN) pinout from Top View to Bottom View	3
anges from Revision D (October 2013) to Revision E	Page
Added Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
	Equation 1, changed From: 10 mV/°F To: 10mv/°C Power Supply Recommendations, changed From: "4-V to 5.5-V power supply" To: "4-V to 30-V power supply: Inges from Revision E (January 2015) to Revision F Changed NDV Package (TO-CAN) pinout from Top View to Bottom View Inges from Revision D (October 2013) to Revision E Added Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device

C	nanges from Revision C (July 2013) to Revision D	Page
•	Changed W to $\mathcal{Q}$	1
•	Changed W to $\Omega$ in Abs Max tablenote.	4

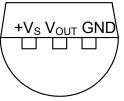


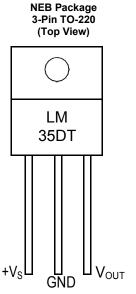
# 5 Pin Configuration and Functions



N.C. = No connection







Tab is connected to the negative pin (GND). **NOTE:** The LM35DT pinout is different than the discontinued LM35DP

#### Pin Functions

PIN					TYPE	DESCRIPTION
NAME	TO46	TO92	TO220	SO8	TIPE	DESCRIPTION
V <sub>OUT</sub>		-	—	1	0	Temperature Sensor Analog Output
N.C.			—	2		No Connection
N.C.			—	3		No connection
GND	_	_	_	4	GROUND	Device ground pin, connect to power supply negative terminal
	_	_	—	5		
N.C.			—	6	—	No Connection
			—	7		
+V <sub>S</sub>	_	_	—	8	POWER	Positive power supply pin

# 6 Specifications

#### Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)(2)</sup>

		MIN	MAX	UNIT
Supply voltage	-0.2	35	V	
Output voltage			6	V
Output current			10	mA
Maximum Junction Temperature, TJmax			150	°C
Storage Temperature, T <sub>stg</sub>	TO-CAN, TO-92 Package	-60	150	ŝ
	TO-220, SOIC Package	-65	150	°C

(1) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.

#### **ESD Ratings**

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

#### **Recommended Operating Conditions**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Specified operating temperature: T <sub>MIN</sub> to	LM35, LM35A	-55	150	
	LM35C, LM35CA	-40	110	°C
I MAX	LM35D	0	100	
Supply Voltage (+V <sub>S</sub> )		4	30	V

#### **Thermal Information**

THERMAL METRIC <sup>(1)(2)</sup>	NDV	LP	D	NEB	UNIT
	3 P	INS	8 PINS	3 PINS	
R <sub>0JA</sub> Junction-to-ambient thermal resistance	400	180	220	90	°C/W
$R_{\scriptscriptstyle \theta JC(top)}$ Junction-to-case (top) thermal resistance	24				C/W

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

(2) For additional thermal resistance information, see *Typical Application*.



#### Electrical Characteristics: LM35A, LM35CA Limits

Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and  $0^{\circ}C \le T_{J} \le 100^{\circ}C$  for the LM35D. V<sub>S</sub> = 5 Vdc and I<sub>LOAD</sub> = 50 µA, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T<sub>MAX</sub> in the circuit of Figure 14.

			LM35A			LM35CA			
PARAMETER	TEST CONDITIONS	ТҮР	TESTED LIMIT <sup>(1)</sup>	DESIGN LIMIT <sup>(2)</sup>	ТҮР	TESTED LIMIT <sup>(1)</sup>	DESIGN LIMIT <sup>(2)</sup>	UNIT	
	T <sub>A</sub> = 25°C	±0.2	±0.5		±0.2	±0.5			
Accuracy (3)	$T_A = -10^{\circ}C$	±0.3			±0.3		±1	°C	
Accuracy	$T_A = T_{MAX}$	±0.4	±1		±0.4	±1		C	
	$T_A = T_{MIN}$	±0.4	±1		±0.4		±1.5		
Nonlinearity <sup>(4)</sup>	$T_{MIN} \le T_A \le T_{MAX},$ -40°C ≤ $T_J \le 125$ °C	±0.18		±0.35	±0.15		±0.3	°C	
Sensor gain	$T_{MIN} \le T_A \le T_{MAX}$	10	9.9		10		9.9		
(average slope)	–40°C ≤ T <sub>J</sub> ≤ 125°C	10	10.1		10		10.1	mV/°C	
(5)	$T_A = 25^{\circ}C$	±0.4	±1		±0.4	±1		mV/mA	
Load regulation <sup>(5)</sup> $0 \le I_L \le 1 \text{ mA}$	$T_{MIN} \le T_A \le T_{MAX},$ -40°C ≤ T <sub>J</sub> ≤ 125°C	±0.5		±3	±0.5		±3		
	T <sub>A</sub> = 25°C	±0.01	±0.05		±0.01	±0.05			
Line regulation <sup>(5)</sup>	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	±0.02		±0.1	±0.02		±0.1	mV/V	
	V <sub>S</sub> = 5 V, 25°C	56	67		56	67			
Quiescent current <sup>(6)</sup>	$V_{\rm S}$ = 5 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	105		131	91		114		
Quiescent current	V <sub>S</sub> = 30 V, 25°C	56.2	68		56.2	68		μA	
	$V_{\rm S}$ = 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	105.5		133	91.5		116		
Change of guigesent	4 V ≤ V <sub>S</sub> ≤ 30 V, 25°C	0.2	1		0.2	1			
Change of quiescent current <sup>(5)</sup>	$4 \text{ V} \le \text{V}_{\text{S}} \le 30 \text{ V},$ -40°C $\le \text{T}_{\text{J}} \le 125$ °C	0.5		2	0.5		2	μA	
Temperature coefficient of quiescent current	–40°C ≤ T <sub>J</sub> ≤ 125°C	0.39		0.5	0.39		0.5	µA/°C	
Minimum temperature for rate accuracy	In circuit of Figure 14, $I_L = 0$	1.5		2	1.5		2	°C	
Long term stability	$T_J = T_{MAX}$ , for 1000 hours	±0.08			±0.08			°C	

(1) Tested Limits are ensured and 100% tested in production.

(2) Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.

(3) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C).

(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.

(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

(6) Quiescent current is defined in the circuit of Figure 14.

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#### Electrical Characteristics: LM35A, LM35CA

Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and 0°C  $\leq$  T<sub>J</sub>  $\leq$  100°C for the LM35D. V<sub>S</sub> = 5 Vdc and I<sub>LOAD</sub> = 50  $\mu$ A, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T<sub>MAX</sub> in the circuit of Figure 14.

			LM35A			LM35CA		
TEST CO	MIN	ТҮР	MAX	TYP	TYP	MAX	UNIT	
			±0.2			±0.2		
T <sub>A</sub> = 25°C	Tested Limit <sup>(2)</sup>			±0.5			±0.5	1
	Design Limit <sup>(3)</sup>							
			±0.3			±0.3		
$T_A = -10^{\circ}C$	Tested Limit <sup>(2)</sup>							
	Design Limit <sup>(3)</sup>						±1	
			±0.4			±0.4		°C
$T_A = T_{MAX}$	Tested Limit <sup>(2)</sup>			±1			±1	
	Design Limit <sup>(3)</sup>							
			±0.4			±0.4		
$T_A = T_{MIN}$	Tested Limit <sup>(2)</sup>			±1				
							±1.5	
$T_{MIN} \le T_A \le T_{MAX},$ -40°C ≤ $T_J \le 125°C$			±0.18			±0.15		°C
	Tested Limit <sup>(2)</sup>							
				±0.35			±0.3	-
$T_{MIN} \le T_A \le T_{MAX}$			10			10		
	Tested Limit <sup>(2)</sup>			9.9		-		
							9.9	
–40°C ≤ T <sub>J</sub> ≤ 125°C			10			10		mV/°C
	Tested Limit <sup>(2)</sup>			10.1				
							10.1	
			±0.4			±0.4		
T₄ = 25°C	Tested Limit <sup>(2)</sup>		-	±1		-	±1	
			±0.5			±0.5		mV/mA
$T_{MIN} \le T_A \le T_{MAX}$	Tested Limit <sup>(2)</sup>							
$-40^{\circ}C \le 1_{J} \le 125^{\circ}C$				±3			±3	
			±0.01			±0.01		
T₄ = 25°C	Tested Limit <sup>(2)</sup>			±0.05			±0.05	
			±0.02			±0.02		mV/V
$4 \text{ V} \leq \text{V}_{\text{S}} \leq 30 \text{ V},$	Tested Limit <sup>(2)</sup>							
–40°C ≤ TJ ≤ 125°C	-			+0.1			+0 1	
	$T_{A} = 25^{\circ}C$ $T_{A} = -10^{\circ}C$ $T_{A} = T_{MAX}$ $T_{A} = T_{MIN}$ $T_{MIN} \leq T_{A} \leq T_{MAX},$ $-40^{\circ}C \leq T_{J} \leq 125^{\circ}C$ $T_{MIN} \leq T_{A} \leq T_{MAX}$ $-40^{\circ}C \leq T_{J} \leq 125^{\circ}C$ $T_{A} = 25^{\circ}C$ $T_{MIN} \leq T_{A} \leq T_{MAX},$ $-40^{\circ}C \leq T_{J} \leq 125^{\circ}C$ $T_{A} = 25^{\circ}C$ $T_{A} = 25^{\circ}C$	Design Limit <sup>(3)</sup> $T_A = -10^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MAX}$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MIN}$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MIN}$ Tested Limit <sup>(2)</sup> 	TEST CONDITIONSMIN $T_A = 25^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = -10^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MAX}$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MIN}$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = T_{MIN}$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_{MIN} \leq T_A \leq T_{MAX}$ $-40^{\circ}C \leq T_J \leq 125^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_{MIN} \leq T_A \leq T_{MAX}$ Design Limit <sup>(3)</sup> Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $-40^{\circ}C \leq T_J \leq 125^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup> $T_A = 25^{\circ}C$ Tested Limit <sup>(2)</sup> Design Limit <sup>(3)</sup>	$\begin{tabular}{ c c c c c } \hline Test CONDITIONS & MIN TYP \\ \hline T_A = 25°C & Tested Limit(2) & & & & & & & & & & & & & & & & & & &$	$\begin{tabular}{ c c c c c c } \hline \textbf{HIN} & \textbf{TYP} & \textbf{MAX} \\ \hline \textbf{I}_A = 25^\circ C & \hline Tested Limit^{(2)} & \pm 0.5 \\ \hline Design Limit^{(3)} & & & & & \\ \hline \textbf{T}_A = -10^\circ C & \hline Tested Limit^{(2)} & \pm 0.3 \\ \hline \textbf{T}_A = -10^\circ C & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{Design Limit^{(3)}} & & & & & \\ \hline \textbf{T}_A = -10^\circ C & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{T}_A = T_{MAX} & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{T}_A = T_{MAX} & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{T}_A = T_{MIN} & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{T}_{ested Limit^{(2)}} & & & & & \\ \hline \textbf{T}_A = T_{MIN} & \hline Tested Limit^{(2)} & & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{MIN} \leq \textbf{T}_A \leq \textbf{T}_{MAX} & \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{A} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 25^\circ C & \hline \hline \textbf{T}_{ested Limit^{(2)}} & & & & \\ \hline \textbf{T}_{a} = 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MIN TYP MAX TYP TYP MAX \\ \hline TA = 25°C & Tested Limit(2) & \pm 0.5 & \pm 0.5 \\ \hline Tested Limit(2) & \pm 0.3 & \pm 0.3 & \\ \hline Tested Limit(2) & \pm 0.3 & \pm 0.3 & \\ \hline Ta = -10°C & Tested Limit(2) & \pm 0.4 & \pm 0.4 & \\ \hline Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MAX} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MAX} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MIN} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MIN} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MIN} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MIN} & Tested Limit(2) & \pm 1 & \\ \hline Ta = T_{MIN} & Ta \leq T_{MAX} & \\ \hline Tested Limit(2) & \pm 1 & \\ \hline Tested Limit(2) & & \\ \hline Ta = 25°C & T_{1} \leq 125°C & \\ \hline Tested Limit(2) & & \\ \hline Ta = 25°C & T_{1} \leq 125°C & \\ \hline Tested Limit(2) & & \\ \hline Ta = 25°C & \hline Tested Limit$

(1) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C). Tested Limits are ensured and 100% tested in production. Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are

(2)

Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated (4) temperature range of the device.

Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating (5) effects can be computed by multiplying the internal dissipation by the thermal resistance.

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<sup>(3)</sup> not used to calculate outgoing quality levels.



### Electrical Characteristics: LM35A, LM35CA (continued)

Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and  $0^{\circ}C \le T_{J} \le 100^{\circ}C$  for the LM35D.  $V_{S} = 5$  Vdc and  $I_{LOAD} = 50 \ \mu$ A, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to  $T_{MAX}$  in the circuit of Figure 14.

DADAMETED	TEST CONDITIONS			LM35A			LM35CA		
PARAMETER	TEST COND	MIN	TYP	MAX	TYP	TYP	MAX	UNIT	
				56			56		
	V <sub>S</sub> = 5 V, 25°C	Tested Limit <sup>(2)</sup>			67			67	
		Design Limit <sup>(3)</sup>							
				105			91		
	V <sub>S</sub> = 5 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>							
Quiescent	40 0 2 1) 2 120 0	Design Limit <sup>(3)</sup>			131			114	
current <sup>(6)</sup>				56.2			56.2		μA
	V <sub>S</sub> = 30 V, 25°C	Tested Limit <sup>(2)</sup>			68			68	
		Design Limit <sup>(3)</sup>							
	V <sub>s</sub> = 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C			105.5			91.5		
		Tested Limit <sup>(2)</sup>							
		Design Limit <sup>(3)</sup>			133			116	
	4 V ≤ V <sub>S</sub> ≤ 30 V, 25°C			0.2			0.2		
		Tested Limit <sup>(2)</sup>			1			1	
Change of		Design Limit <sup>(3)</sup>							
quiescent current <sup>(5)</sup>	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C			0.5			0.5		μA
		Tested Limit <sup>(2)</sup>							
		Design Limit <sup>(3)</sup>			2			2	
Temperature				0.39			0.39		
coefficient of	–40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>							µA/°C
quiescent current		Design Limit <sup>(3)</sup>			0.5			0.5	
Minimum				1.5			1.5		
temperature for	In circuit of Figure 14, $I_L = 0$	Tested Limit <sup>(2)</sup>							°C
rate accuracy		Design Limit <sup>(3)</sup>			2			2	
Long term stability	$T_J = T_{MAX}$ , for 1000 hours			±0.08			±0.08		°C

(6) Quiescent current is defined in the circuit of Figure 14.



### Electrical Characteristics: LM35, LM35C, LM35D Limits

Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and 0°C  $\leq$  T<sub>J</sub>  $\leq$  100°C for the LM35D. V<sub>S</sub> = 5 Vdc and I<sub>LOAD</sub> = 50  $\mu$ A, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T<sub>MAX</sub> in the circuit of Figure 14

			LM35		LI	M35C, LM3	5D		
PARAMETER	TEST CONDITIONS	ТҮР	TESTED LIMIT <sup>(1)</sup>	DESIGN LIMIT <sup>(2)</sup>	ТҮР	TESTED LIMIT <sup>(1)</sup>	DESIGN LIMIT <sup>(2)</sup>	UNIT	
	T <sub>A</sub> = 25°C	±0.4	±1		±0.4	±1			
Accuracy, LM35,	$T_A = -10^{\circ}C$	±0.5			±0.5		±1.5	Э°	
LM35C <sup>(3)</sup>	$T_A = T_{MAX}$	±0.8	±1.5		±0.8		±1.5	C	
	$T_A = T_{MIN}$	±0.8		±1.5	±0.8		±2		
	T <sub>A</sub> = 25°C				±0.6	±1.5			
Accuracy, LM35D (3)	$T_A = T_{MAX}$				±0.9		±2	°C	
	$T_A = T_{MIN}$				±0.9		±2		
Nonlinearity <sup>(4)</sup>	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , -40°C ≤ T <sub>J</sub> ≤ 125°C	±0.3		±0.5	±0.2		±0.5	°C	
Sensor gain	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , -40°C ≤ T <sub>J</sub> ≤ 125°C	10	9.8		10		9.8	mV/°C	
(average slope)		10	10.2		10		10.2		
Load regulation <sup>(5)</sup>	T <sub>A</sub> = 25°C	±0.4	±2		±0.4	±2			
$0 \le I_L \le 1 \text{ mA}$	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , -40°C ≤ T <sub>J</sub> ≤ 125°C	±0.5		±5	±0.5		±5	mV/mA	
	T <sub>A</sub> = 25°C	±0.01	±0.1		±0.01	±0.1			
Line regulation <sup>(5)</sup>	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	±0.02		±0.2	±0.02		±0.2	mV/V	
	V <sub>S</sub> = 5 V, 25°C	56	80		56	80			
Quiescent current <sup>(6)</sup>	$V_{\rm S} = 5 \text{ V}, -40^{\circ}\text{C} \le T_{\rm J} \le 125^{\circ}\text{C}$	105		158	91		138	μA	
Quiescent current	V <sub>S</sub> = 30 V, 25°C	56.2	82		56.2	82		μΑ	
	$V_S$ = 30 V, -40°C ≤ $T_J$ ≤ 125°C	105.5		161	91.5		141		
Change of guiescent	$4 \text{ V} \leq \text{V}_{\text{S}} \leq 30 \text{ V}, 25^{\circ}\text{C}$	0.2	2		0.2	2			
current <sup>(5)</sup>	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	0.5		3	0.5		3	μA	
Temperature coefficient of quiescent current	–40°C ≤ T <sub>J</sub> ≤ 125°C	0.39		0.7	0.39		0.7	µA/°C	
Minimum temperature for rate accuracy	In circuit of Figure 14, $I_L = 0$	1.5		2	1.5		2	°C	
Long term stability	$T_J = T_{MAX}$ , for 1000 hours	±0.08			±0.08			°C	

(1) Tested Limits are ensured and 100% tested in production.

Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are (2) not used to calculate outgoing quality levels.

Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C). (3)

(4) Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.

Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating (5)effects can be computed by multiplying the internal dissipation by the thermal resistance. Quiescent current is defined in the circuit of Figure 14.

(6)



#### Electrical Characteristics: LM35, LM35C, LM35D

Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and 0°C  $\leq$  T<sub>J</sub>  $\leq$  100°C for the LM35D. V<sub>S</sub> = 5 Vdc and I<sub>LOAD</sub> = 50  $\mu$ A, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to T<sub>MAX</sub> in the circuit of Figure 14.

DADAMETED	TEAT OO			LM35		LM3	5C, LM35	D		
PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
				±0.4			±0.4			
	T <sub>A</sub> = 25°C	Tested Limit <sup>(2)</sup>			±1			±1		
		Design Limit <sup>(3)</sup>								
				±0.5			±0.5			
	$T_A = -10^{\circ}C$	Tested Limit <sup>(2)</sup>								
Accuracy, LM35,		Design Limit <sup>(3)</sup>						±1.5	°C	
LM35C <sup>(1)</sup>				±0.8			±0.8		ι,	
	$T_A = T_{MAX}$	Tested Limit <sup>(2)</sup>			±1.5					
		Design Limit <sup>(3)</sup>						±1.5		
	T <sub>A</sub> = T <sub>MIN</sub>			±0.8			±0.8			
		Tested Limit <sup>(2)</sup>								
		Design Limit <sup>(3)</sup>			±1.5			±2		
							±0.6			
	T <sub>A</sub> = 25°C	Tested Limit <sup>(2)</sup>						±1.5		
		Design Limit <sup>(3)</sup>							°C	
Accuracy, LM35D <sup>(1)</sup>							±0.9			
	$T_A = T_{MAX}$	Tested Limit <sup>(2)</sup>								
LIVISSD		Design Limit <sup>(3)</sup>						±2		
	T <sub>A</sub> = T <sub>MIN</sub>						±0.9			
		Tested Limit <sup>(2)</sup>								
		Design Limit <sup>(3)</sup>						±2		
				±0.3			±0.2		°C	
Nonlinearity <sup>(4)</sup>	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , –40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>								
-	-40 C 3 1 3 125 C	Design Limit <sup>(3)</sup>			±0.5			±0.5	_	
				10			10			
	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , -40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>			9.8					
Sensor gain	-40 C 3 1 3 125 C	Design Limit <sup>(3)</sup>						9.8		
(average slope)				10			10		mV/°C	
		Tested Limit <sup>(2)</sup>			10.2					
		Design Limit <sup>(3)</sup>						10.2		
		-		±0.4			±0.4			
	T <sub>A</sub> = 25°C	Tested Limit <sup>(2)</sup>			±2			±2		
Load regulation <sup>(5)</sup>		Design Limit <sup>(3)</sup>								
$0 \le I_L \le 1 \text{ mA}$				±0.5			±0.5		mV/mA	
	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub> , –40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>								
	-40 C ≥ 1j ≤ 125 C	Design Limit <sup>(3)</sup>			±5			±5		

(1) Accuracy is defined as the error between the output voltage and 10 mv/°C times the case temperature of the device, at specified conditions of voltage, current, and temperature (expressed in °C). Tested Limits are ensured and 100% tested in production. Design Limits are ensured (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are

(2)

(3) not used to calculate outgoing quality levels.

Non-linearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated (4) temperature range of the device.

Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating (5) effects can be computed by multiplying the internal dissipation by the thermal resistance.

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Electrical Characteristics: LM35, LM35C, LM35D (continued)

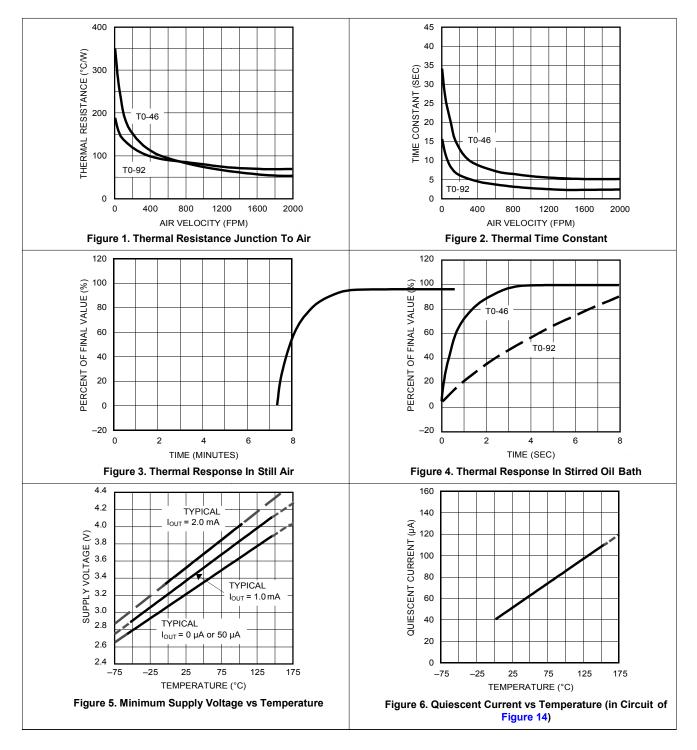
Unless otherwise noted, these specifications apply:  $-55^{\circ}C \le T_{J} \le 150^{\circ}C$  for the LM35 and LM35A;  $-40^{\circ}C \le T_{J} \le 110^{\circ}C$  for the LM35C and LM35CA; and  $0^{\circ}C \le T_{J} \le 100^{\circ}C$  for the LM35D.  $V_{S} = 5$  Vdc and  $I_{LOAD} = 50 \ \mu$ A, in the circuit of Full-Range Centigrade Temperature Sensor. These specifications also apply from 2°C to  $T_{MAX}$  in the circuit of Figure 14.

			LM35		LM3	5C, LM35	D			
PARAMETER	TEST CONDI	TIONS	MIN	ТҮР	MAX	MIN	ТҮР	MAX	UNIT	
				±0.01			±0.01			
	T <sub>A</sub> = 25°C	Tested Limit <sup>(2)</sup>			±0.1					
		Design Limit <sup>(3)</sup>						±0.1		
Line regulation <sup>(5)</sup>		-		±0.02			±0.02		mV/V	
	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>								
	-40 0 2 1 3 2 1 2 0 0	Design Limit <sup>(3)</sup>			±0.2			±0.2		
				56			56			
	V <sub>s</sub> = 5 V, 25°C	Tested Limit <sup>(2)</sup>			80			80		
		Design Limit <sup>(3)</sup>								
	V <sub>S</sub> = 5 V, –40°C ≤ T <sub>J</sub> ≤ 125°C			105			91			
		Tested Limit <sup>(2)</sup>								
Quiescent current <sup>(6)</sup>	120 0	Design Limit <sup>(3)</sup>			158			138		
				56.2			56.2		μA	
	V <sub>s</sub> = 30 V, 25°C	Tested Limit <sup>(2)</sup>			82			82		
		Design Limit <sup>(3)</sup>								
				105.5			91.5			
	V <sub>S</sub> = 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>								
	10 0 1 1 1 1 20 0	Design Limit <sup>(3)</sup>			161			141		
				0.2			0.2			
	4 V ≤ V <sub>S</sub> ≤ 30 V, 25°C	Tested Limit <sup>(2)</sup>						2		
Change of		Design Limit <sup>(3)</sup>			2					
quiescent current <sup>(5)</sup>				0.5			0.5		μA	
	4 V ≤ V <sub>S</sub> ≤ 30 V, -40°C ≤ T <sub>J</sub> ≤ 125°C	Tested Limit <sup>(2)</sup>								
	10 0 1 1 1 1 20 0	Design Limit <sup>(3)</sup>			3			3		
Temperature				0.39			0.39			
coefficient of	–40°C ≤ TJ ≤ 125°C	Tested Limit <sup>(2)</sup>						µA/°C		
quiescent current		Design Limit <sup>(3)</sup>			0.7			0.7	•	
Minimum				1.5			1.5			
temperature for	In circuit of Figure 14, $I_L = 0$	Tested Limit <sup>(2)</sup>							°C	
rate accuracy	-	Design Limit <sup>(3)</sup>			2			2		
Long term stability	$T_J = T_{MAX}$ , for 1000 hours			±0.08			±0.08		°C	

(6) Quiescent current is defined in the circuit of Figure 14.

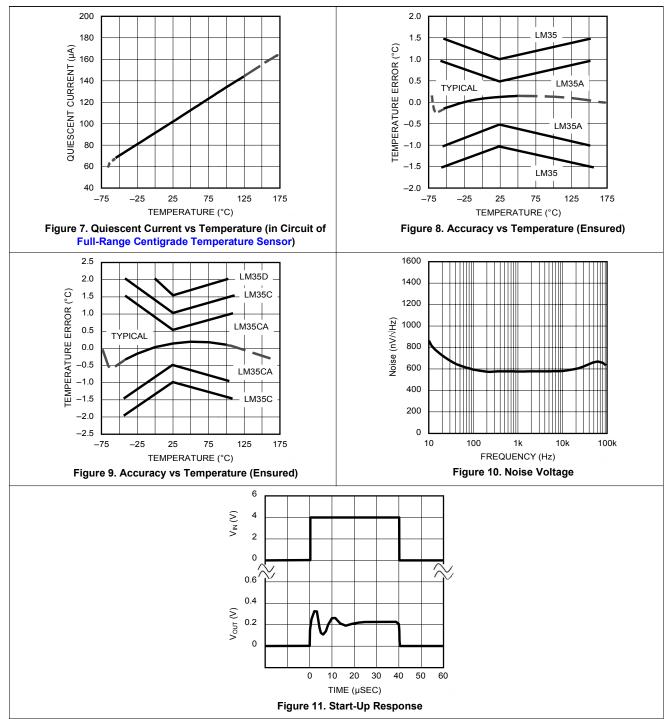


### **Typical Characteristics**





#### **Typical Characteristics (continued)**





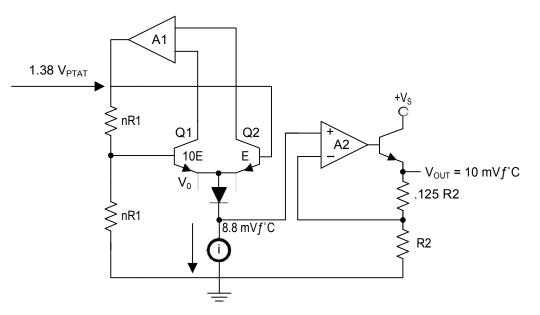
## 7 Detailed Description

#### Overview

The LM35-series devices are precision integrated-circuit temperature sensors, with an output voltage linearly proportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of  $\pm \frac{1}{4}$  °C at room temperature and  $\pm \frac{3}{4}$  °C over a full -55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60  $\mu$ A from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a -55°C to 150°C temperature range, while the LM35C device is rated for a -40°C to 110°C range (-10° with improved accuracy). The temperature-sensing element is comprised of a delta-V BE architecture.

The temperature-sensing element is then buffered by an amplifier and provided to the VOUT pin. The amplifier has a simple class A output stage with typical  $0.5-\Omega$  output impedance as shown in the *Functional Block Diagram*. Therefore the LM35 can only source current and it's sinking capability is limited to 1  $\mu$ A.

#### Functional Block Diagram



#### **Feature Description**

#### LM35 Transfer Function

The accuracy specifications of the LM35 are given with respect to a simple linear transfer function:

 $V_{OUT}$  = 10 mv/°C × T

where

- V<sub>OUT</sub> is the LM35 output voltage
- T is the temperature in °C

(1)

#### 7.4 Device Functional Modes

The only functional mode of the LM35 is that it has an analog output directly proportional to temperature.

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# 8 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### Application Information

The features of the LM35 make it suitable for many general temperature sensing applications. Multiple package options expand on it's flexibility.

#### Capacitive Drive Capability

Like most micropower circuits, the LM35 device has a limited ability to drive heavy capacitive loads. Alone, the LM35 device is able to drive 50 pF without special precautions. If heavier loads are anticipated, isolating or decoupling the load with a resistor is easy (see Figure 12). The tolerance of capacitance can be improved with a series R-C damper from output to ground (see Figure 13).

When the LM35 device is applied with a 200- $\Omega$  load resistor as shown in Figure 16, Figure 17, or Figure 19, the device is relatively immune to wiring capacitance because the capacitance forms a bypass from ground to input and not on the output. However, as with any linear circuit connected to wires in a hostile environment, performance is affected adversely by intense electromagnetic sources (such as relays, radio transmitters, motors with arcing brushes, and SCR transients), because the wiring acts as a receiving antenna and the internal junctions act as rectifiers. For best results in such cases, a bypass capacitor from V<sub>IN</sub> to ground and a series R-C damper, such as 75  $\Omega$  in series with 0.2 or 1  $\mu$ F from output to ground, are often useful. Examples are shown in Figure 13, Figure 24, and Figure 25.

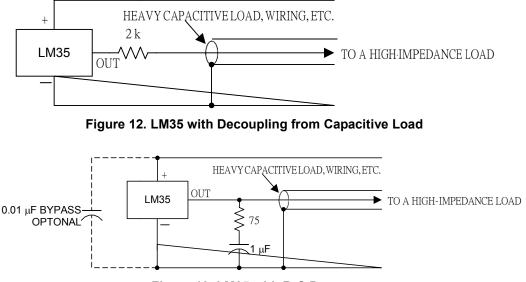
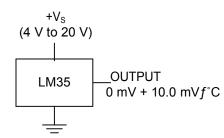


Figure 13. LM35 with R-C Damper



### Basic Centigrade Temperature Sensor





#### Design Requirements

PARAMETER	VALUE				
Accuracy at 25°C	±0.5°C				
Accuracy from –55 °C to 150°C	±1°C				
Temperature Slope	10 mV/°C				

#### **Table 1. Design Parameters**

#### **Detailed Design Procedure**

Because the LM35 device is a simple temperature sensor that provides an analog output, design requirements related to layout are more important than electrical requirements. For a detailed description, refer to the *Layout*.

#### Application Curve

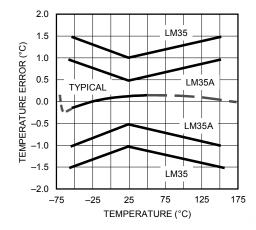


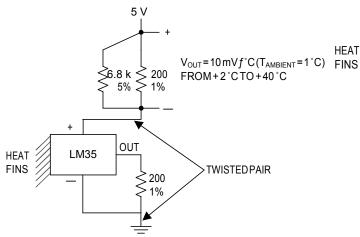
Figure 15. Accuracy vs Temperature (Ensured)

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#### LM35 SNIS159G – AUGUST 1999 – REVISED AUGUST 2016

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### 8.3 System Examples





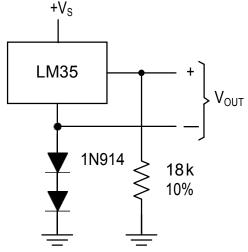
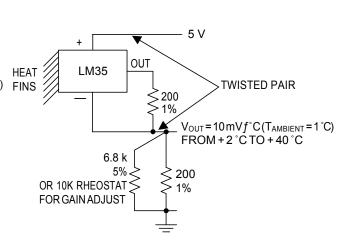
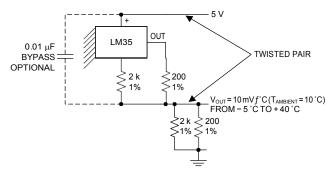


Figure 18. Temperature Sensor, Single Supply (-55° to +150°C)



#### Figure 17. Two-Wire Remote Temperature Sensor (Output Referred to Ground)







System Examples (continued)

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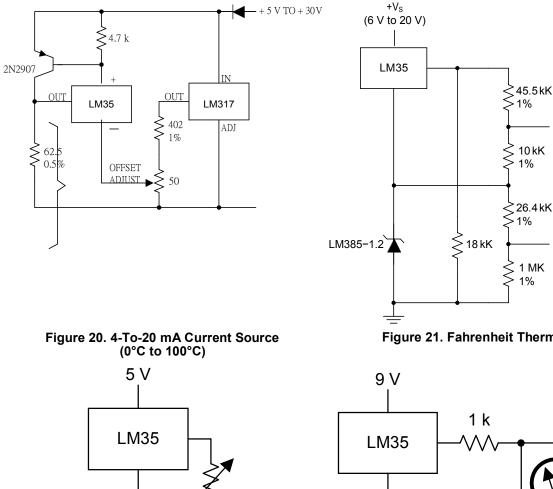
45.5 kK

10 kK

1 MK 1%

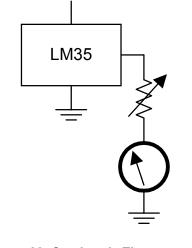
1%

1%



 $V_{OUT} = +1 \text{ mV} f^{\circ}F$ 

Figure 21. Fahrenheit Thermometer





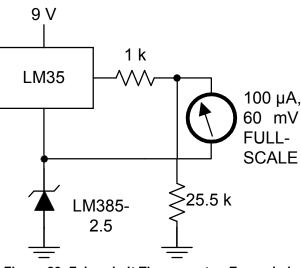
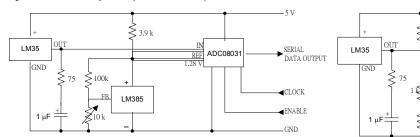


Figure 23. Fahrenheit Thermometer, Expanded Scale Thermometer (50°F to 80°F, for Example Shown)

System Examples (continued)



#### Figure 24. Temperature to Digital Converter (Serial Output) (128°C Full Scale)

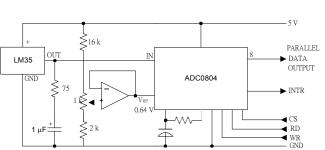
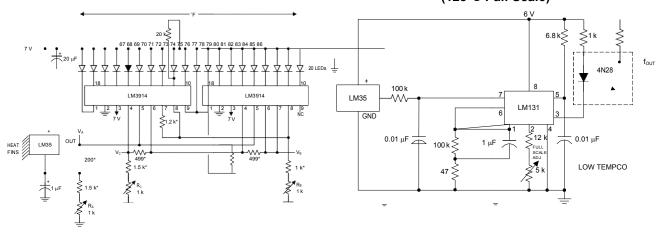


Figure 25. Temperature to Digital Converter (Parallel TRI-STATE Outputs for Standard Data Bus to μP Interface) (128°C Full Scale)



\*=1% or 2% film resistor

Trim  $R_B$  for  $V_B$  = 3.075 V

Trim  $R_c$  for  $V_c = 1.955$  V

Trim  $R_A$  for  $V_A$  = 0.075 V + 100 mV/°C ×T<sub>ambient</sub>

Example,  $V_A$  = 2.275 V at 22°C

# Figure 26. Bar-Graph Temperature Display (Dot Mode)

Figure 27. LM35 With Voltage-To-Frequency Converter and Isolated Output (2°C to 150°C; 20 to 1500 Hz)



### 9 Power Supply Recommendations

The LM35 device has a very wide 4-V to 30-V power supply voltage range, which makes it ideal for many applications. In noisy environments, TI recommends adding a 0.1  $\mu$ F from V+ to GND to bypass the power supply voltage. Larger capacitances maybe required and are dependent on the power-supply noise.

### 10 Layout

#### Layout Guidelines

The LM35 is easily applied in the same way as other integrated-circuit temperature sensors. Glue or cement the device to a surface and the temperature should be within about 0.01°C of the surface temperature.

The 0.01°C proximity presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature were much higher or lower than the surface temperature, the actual temperature of the LM35 die would be at an intermediate temperature between the surface temperature and the air temperature; this is especially true for the TO-92 plastic package. The copper leads in the TO-92 package are the principal thermal path to carry heat into the device, so its temperature might be closer to the air temperature than to the surface temperature.

Ensure that the wiring leaving the LM35 device is held at the same temperature as the surface of interest to minimize the temperature problem. The easiest fix is to cover up these wires with a bead of epoxy. The epoxy bead will ensure that the leads and wires are all at the same temperature as the surface, and that the temperature of the LM35 die is not affected by the air temperature.

The TO-46 metal package can also be soldered to a metal surface or pipe without damage. Of course, in that case the V- terminal of the circuit will be grounded to that metal. Alternatively, mount the LM35 inside a sealedend metal tube, and then dip into a bath or screw into a threaded hole in a tank. As with any IC, the LM35 device and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to insure that moisture cannot corrode the LM35 device or its connections.

These devices are sometimes soldered to a small light-weight heat fin to decrease the thermal time constant and speed up the response in slowly-moving air. On the other hand, a small thermal mass may be added to the sensor, to give the steadiest reading despite small deviations in the air temperature.

	TO, no heat sink	TO <sup>(1)</sup> , small heat fin	TO-92, no heat sink	TO-92 <sup>(2)</sup> , small heat fin	SOIC-8, no heat sink	SOIC-8 <sup>(2)</sup> , small heat fin	TO-220, no heat sink
Still air	400°C/W	100°C/W	180°C/W	140°C/W	220°C/W	110°C/W	90°C/W
Moving air	100°C/W	40°C/W	90°C/W	70°C/W	105°C/W	90°C/W	26°C/W
Still oil	100°C/W	40°C/W	90°C/W	70°C/W	_	—	_
Stirred oil	50°C/W	30°C/W	45°C/W	40°C/W	_	_	_
(Clamped to metal, Infinite heat sink)	(24°	°C/W)	_	_	(55°)	_	

Table 2. Temperature Rise of LM35 Due To Self-heating (Thermal Resistance,  $R_{\theta JA}$ )

(1) Wakefield type 201, or 1-in disc of 0.02-in sheet brass, soldered to case, or similar.

(2) TO-92 and SOIC-8 packages glued and leads soldered to 1-in square of 1/16-in printed circuit board with 2-oz foil or similar.

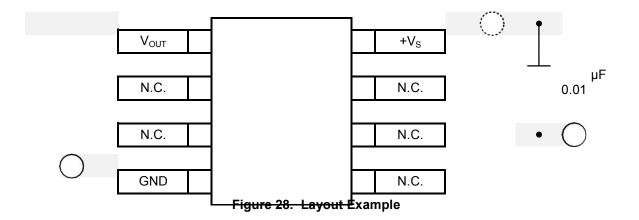


### Layout Example



VIA to ground plane

> VIA to power plane





### **11** Device and Documentation Support

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#### **Electrostatic Discharge Caution**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

#### 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



17-Mar-2017

# PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM35AH	ACTIVE	ТО	NDV	3	500	TBD	Call TI	Call TI	-55 to 150	( LM35AH ~ LM35AH)	Samples
LM35AH/NOPB	ACTIVE	то	NDV	3	500	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-55 to 150	( LM35AH ~ LM35AH)	Samples
LM35CAH	ACTIVE	то	NDV	3	500	TBD	Call TI	Call TI	-40 to 110	( LM35CAH ~ LM35CAH)	Samples
LM35CAH/NOPB	ACTIVE	то	NDV	3	500	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 110	( LM35CAH ~ LM35CAH)	Samples
LM35CAZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM35 CAZ	Samples
LM35CAZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 110	LM35 CAZ	Samples
LM35CH	ACTIVE	ТО	NDV	3	500	TBD	Call TI	Call TI	-40 to 110	( LM35CH ~ LM35CH)	Samples
LM35CH/NOPB	ACTIVE	то	NDV	3	500	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 110	( LM35CH ~ LM35CH)	Samples
LM35CZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM35 CZ	Samples
LM35CZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 110	LM35 CZ	Samples
LM35DH	ACTIVE	ТО	NDV	3	1000	TBD	Call TI	Call TI	0 to 70	( LM35DH ~ LM35DH)	Samples
LM35DH/NOPB	ACTIVE	ТО	NDV	3	1000	Green (RoHS & no Sb/Br)	Call TI   POST-PLATE	Level-1-NA-UNLIM	0 to 70	( LM35DH ~ LM35DH)	Samples
LM35DM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	0 to 100	LM35D M	
LM35DM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 100	LM35D M	Samples
LM35DMX	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 100	LM35D M	
LM35DMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 100	LM35D M	Samples
LM35DT	NRND	TO-220	NEB	3	45	TBD	Call TI	Call TI	0 to 100	LM35DT	
LM35DT/NOPB	ACTIVE	TO-220	NEB	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 100	LM35DT	Samples



TEXAS PACKAGE OPTION ADDENDUM

INSTRUMENTS

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17-Mar-2017

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM35DZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM35 DZ	Samples
LM35DZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM35 DZ	Samples
LM35DZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	0 to 100	LM35 DZ	Samples
LM35H	ACTIVE	ТО	NDV	3	500	TBD	Call TI	Call TI	-55 to 150	( LM35H ~ LM35H)	Samples
LM35H/NOPB	ACTIVE	то	NDV	3	500	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-55 to 150	( LM35H ~ LM35H)	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



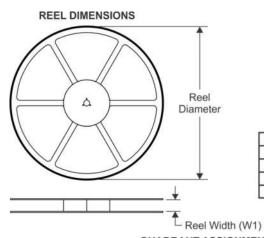
17-Mar-2017

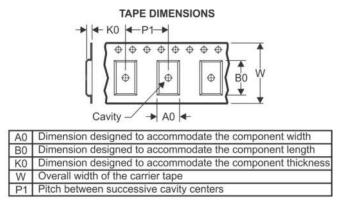
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www.ti.com 15-Aug-2016

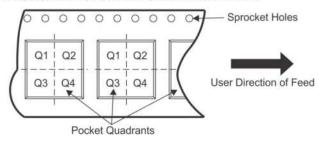
### TAPE AND REEL INFORMATION





PACKAGE MATERIALS IN FORMATION

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



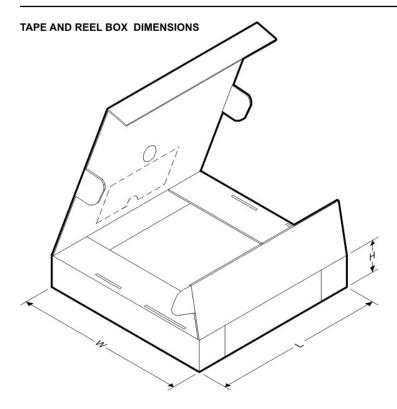
*All	dimensions	are	nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM35DMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM35DMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1



# PACKAGE MATERIALS INFORMATION

15-Aug-2016



\*All dimensions are nominal

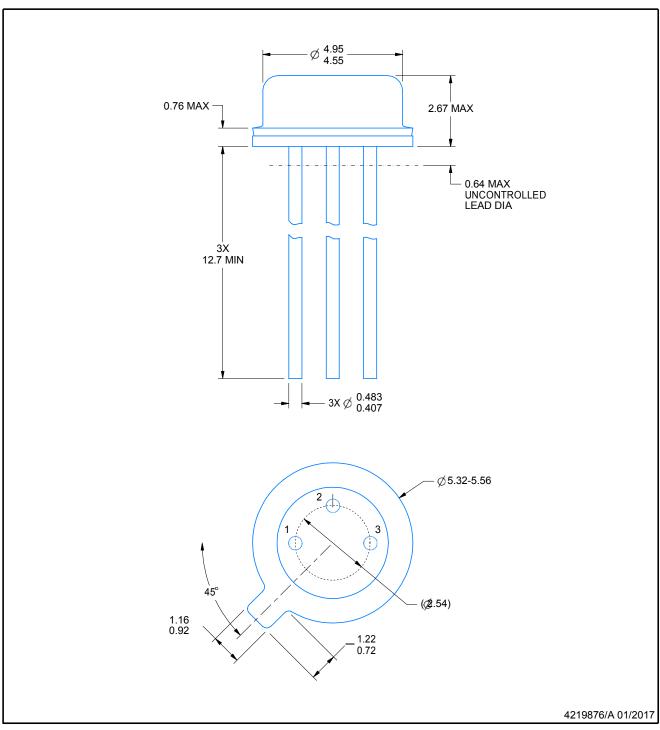
Device	Package Type	Type Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)	
LM35DMX	SOIC	D	8	2500	367.0	367.0	35.0	
LM35DMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0	

# NDV0003H

# **PACKAGE OUTLINE**

# TO-CAN - 2.67 mm max height

TO-46



NOTES:

\_ -

- -

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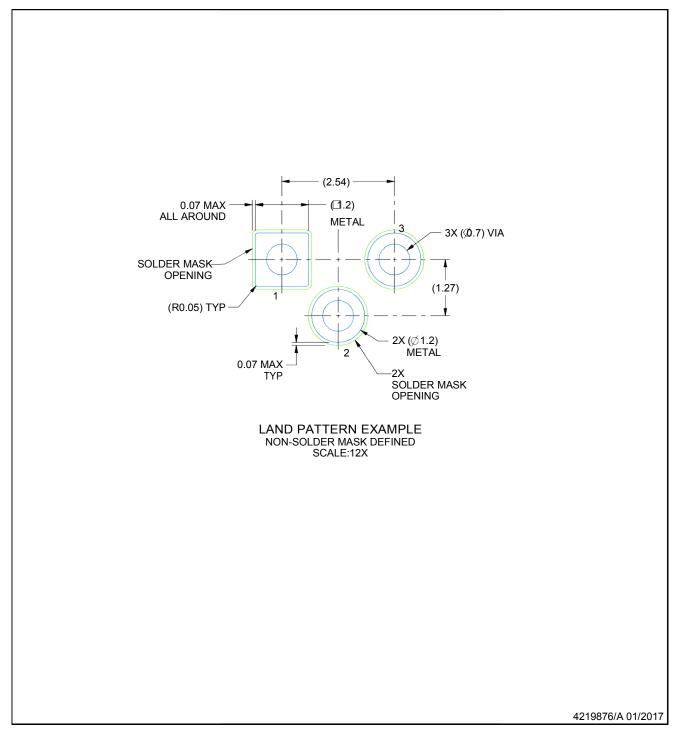
All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration TO-46.

# **EXAMPLE BOARD LAYOUT**

# **NDV0003H**

# TO-CAN - 2.67 mm max height

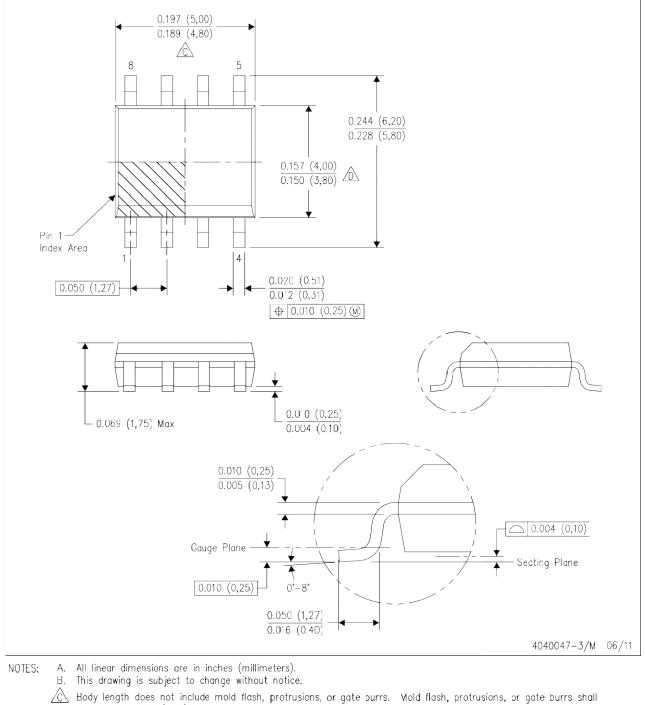
TO-46





D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interleac flash shall not exceed 0.017 (0,43) each side. E. Reference JEDEC MS-012 variation AA.



# **GENERIC PACKAGE VIEW**

# TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040001-2/F

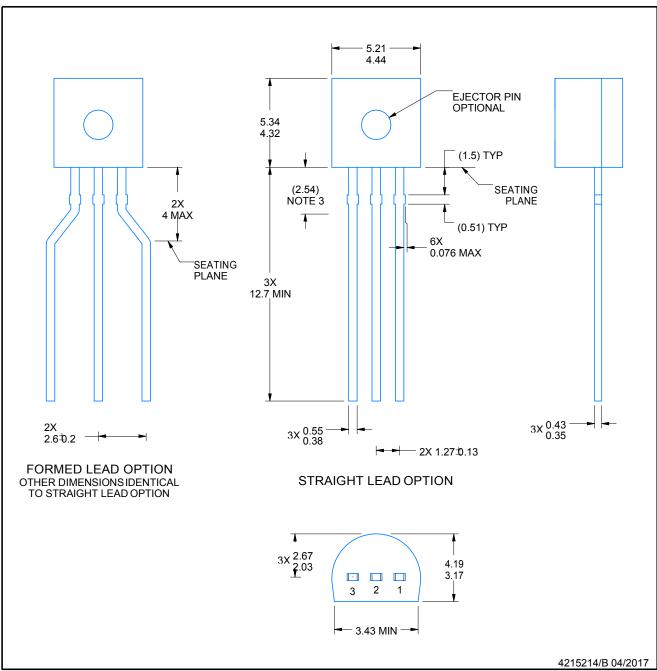


# LP0003A



### TO-92 - 5.34 mm max height

TO-92



NOTES:

- Lead dimensions are not controlled within this area.
   Reference JEDEC TO-226, variation AA.
- 5. Shipping method:
  - a. Straight lead option available in bulk pack only.

  - b. Formed lead option available in tape and reel or ammo pack.
    c. Specific products can be offered in limited combinations of shipping medium and lead options.
    d. Consult product folder for more information on available options.

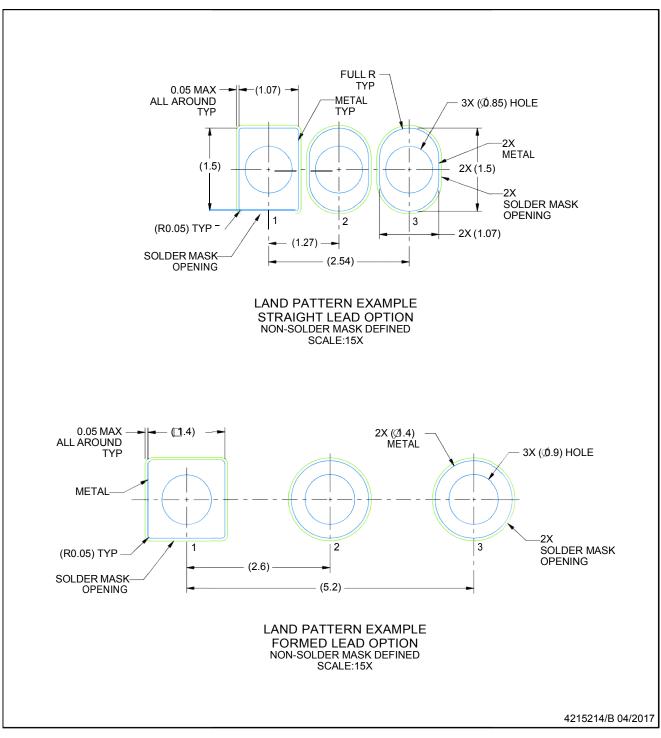
<sup>1.</sup> All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.

# LP0003A

# **EXAMPLE BOARD LAYOUT**

# TO-92 - 5.34 mm max height

TO-92



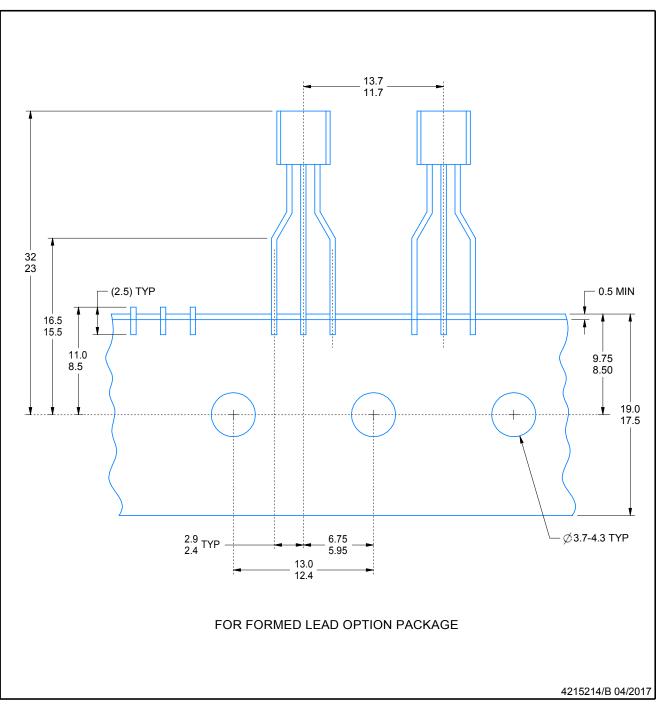


# LP0003A

# TAPE SPECIFICATIONS

# TO-92 - 5.34 mm max height

TO-92



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Document: Datasheet

Date: 20-Jun-12

Model #: 3732

Product's Page: www.sunrom.com/p-1141.html

## **DHT11 - Humidity and Temperature Sensor**

The DHT11 is a basic, low-cost digital temperature and humidity sensor. It uses a capacitive humidity sensor and a thermistor to measure the surrounding air, and spits out a digital signal on the data pin (no analog input pins needed).

Its fairly simple to use, but requires careful timing to grab data. The only real downside of this sensor is you can only get new data from it once every 2 seconds.

### **Features**

- Full range temperature compensated
- Relative humidity and temperature measurement
- Calibrated digital signal
- Outstanding long-term stability
- Extra components not needed
- Long transmission distance
- Low power consumption
- 4 pins packaged and fully interchangeable

## **Details**

This sensor includes a resistive-type humidity measurement component and an NTC temperature measurement component, and connects to a highperformance 8-bit microcontroller, offering excellent quality, fast response, anti-interference ability and cost-effectiveness. Each DHT11 element is strictly calibrated in the laboratory that is extremely accurate on humidity calibration. The calibration coefficients are stored as programmes in the OTP memory, which are used by the sensor's internal signal detecting process.

The single-wire serial interface makes system integration quick and easy. Its small size, low power consumption and up-to-20 meter signal transmission making it the best choice for various applications, including those most demanding ones. The component is 4-pin single row pin package.



## **Specifications**

ltem	Measurement Range	Humidity Accuracy	Temperature Accuracy	Resolution	Package
DHT11	20-90%RH 0-50 ℃	±5%RH	±2℃	1	4 Pin Single Row

Parameters	Conditions	Minimum	Typical	Maximum
Humidity		1		
Resolution		1%RH	1%RH	1%RH
			8 Bit	
Repeatability			$\pm$ 1%RH	
Accuracy	25℃		$\pm$ 4%RH	
	<b>0-50</b> ℃			$\pm$ 5%RH
Interchangeability	Fully Interchangeable			
Measurement	0°C	30%RH		90%RH
Range	25℃	20%RH		90%RH
	50℃	20%RH		80%RH
Response Time	1/e(63%)25℃,	6 S	10 S	15 S
(Seconds)	1m/s Air			
Hysteresis			$\pm$ 1%RH	
Long-Term Stability	Typical		$\pm$ 1%RH/year	
Temperature				
Resolution		1℃	1℃	1°C
		8 Bit	8 Bit	8 Bit
Repeatability			±1℃	
Accuracy		±1℃		±2℃
Measurement		0°C		50°C
Range				
Response Time	1/e(63%)	6 S		30 S
(Seconds)				

Item	Condition	Min	Typical	Max	Unit
Power supply	DC	3	5	5.5	V
Current supply	Measuring	0.5		2.5	mA
	Stand-by	100	Null	150	uA
	Average	0.2	Null	1	mA

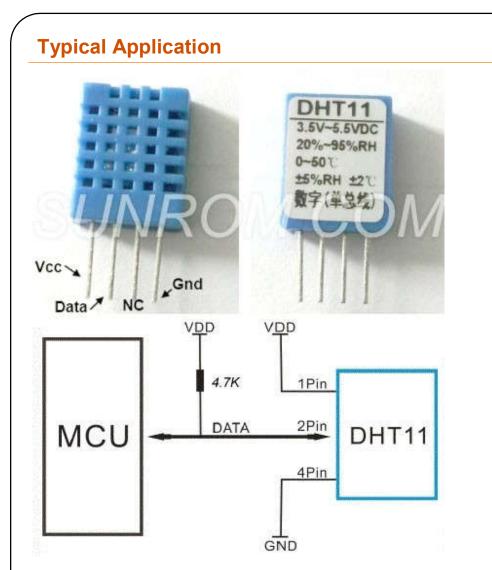
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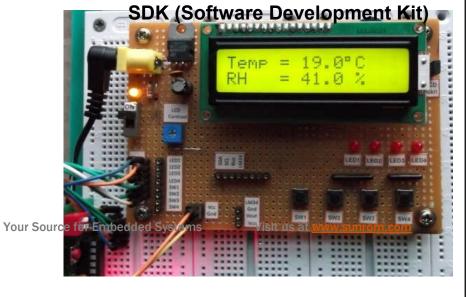


DHT11's power supply is 3-5.5V DC. When power is supplied to the sensor, do not send any instruction to the sensor in within one second in order to pass the unstable status. One capacitor valued 100nF can be added between VDD and GND for power filtering.

Download source code + project articles by clicking following link

http://www.sunrom.com/files/3732.zip

It contains details for AVR, PIC and Arduino projects.



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## Communication Process: Serial Interface (Single-Wire Two-Way)

The interesting thing in this module is the protocol that uses to transfer data. All the sensor readings are sent using a single wire bus which reduces the cost and extends the distance. In order to send data over a bus you have to describe the way the data will be transferred, so that transmitter and receiver can understand what says each other. This is what a protocol does. It describes the way the data are transmitted. On DHT-11 the 1-wire data bus is pulled up with a resistor to VCC. So if nothing is occurred the voltage on the bus is equal to VCC.

Communication Format can be seperated into three stages

- 1) Request
- 2) Response
- 3) Data Reading
- 1) **Request:** To make the DHT-11 to send you the sensor readings you have to send it a request. The request is, to pull down the bus for more than **18ms** in order to give DHT time to understand it and then pull it up for **40uS**.

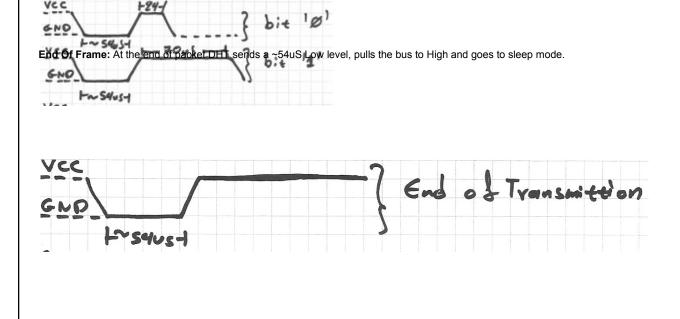
UC Request 2) Response: What comes after the request is the DHT-11 response. This is an automatic reply from DHT which indicates that DHT received your request. The response is ~54uS low and 80uS high. - 80 us Reading: What will come after the response is the sensor data. The data will be packed in nts of 8-bits each. Totally 5×8 =40bits. a packet Packet perature read in Celsius, integral & decimal and the last nal. Following First two serme gment is the Check Sum which is the sum of the 4 - 8-bitmrom Technologies bit your Source for Embedded Systems bit Visit usat was unrom.com TEXAS Instruments www.ti.com

segments. If Check Sum's value isn't the same as the sum of the first 4 segments that means that data received isn't correct.

How to Identify Bits: Each bit sent is a follow of ~54uS Low in the bus and ~24uS to 70uS High depending on the value of the bit.

Bit '0' : ~54uS Low and ~24uS High Bit '1' : ~54uS

Low and ~70uS High

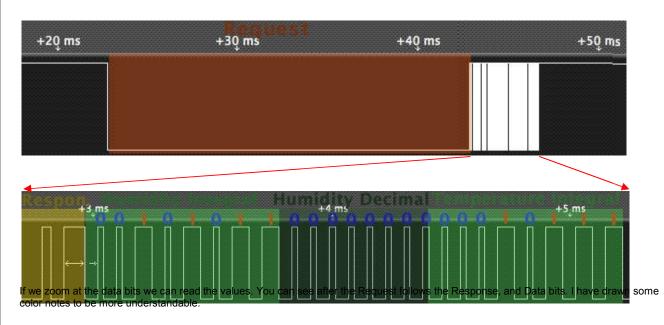


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Logic Analyzer Snapshots: In the following image you can see the request sent from the MCU to the DHT and following the packet. Because the request has very long duration as you can see is about 20mS and packet received is in uS we can't view the data bits. So it is exapanded in next view.



If we decode the above data we have.

Humidity 0b00101011.0b00000000 = 43.0% (43 is integral part and .0 is decimal part) Temperature 0b00010111 = 23 C.

The last two segments can't be seen in this image because of zoom.

### Implementation:

What we have to do to read a DHT-11 sensor is:

- 1) Send request
- 2) Read response
- 3) Read each data segment and save it to a buffer
- 4) Sum the segments and check if the result is the same as CheckSum

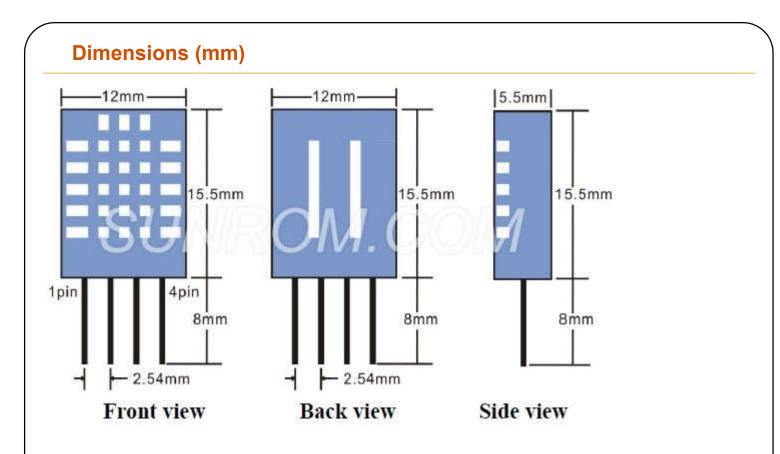
If the CheckSum is correct, the values are correct so we can use them. If CheckSum is wrong we discard the packet.

To read the data bits can use a counter and start count uSeconds of High level. For counts > 24uS we replace with bit '1'. For counts <=24 we replace with bit'0'

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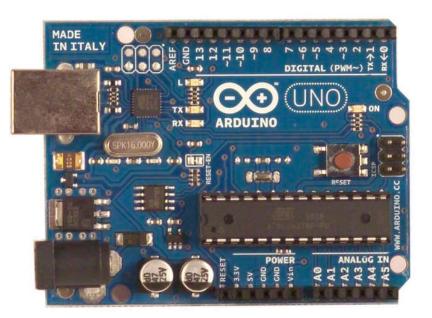




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# Arduino UNO



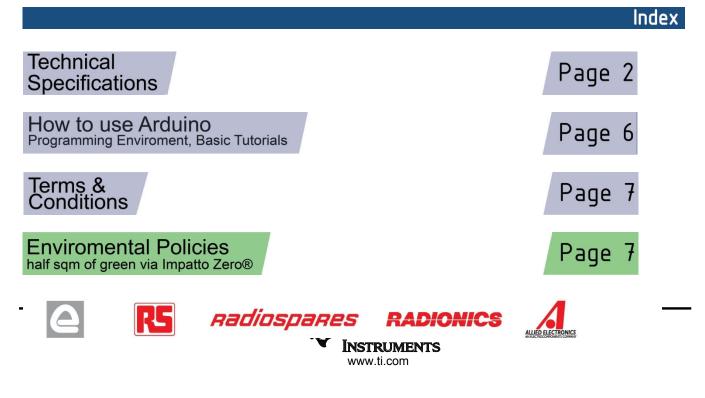
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#### Product Overview

The Arduino Uno is a microcontroller board based on the ATmega328 (<u>datasheet</u>). It has 14 digital input/output pins (of which 6 can be used as PWM outputs), 6 analog inputs, a 16 MHz crystal oscillator, a USB connection, a power jack, an ICSP header, and a reset button. It contains everything needed to support the microcontroller; simply connect it to a computer with a USB cable or power it with a AC-to-DC adapter or battery to get started. The Uno differs from all preceding boards in that it does not use the FTDI USB-to-serial driver chip. Instead, it features the Atmega8U2 programmed as a USB-to-serialconverter.

"Uno" means one in Italian and is named to mark the upcoming release of Arduino 1.0. The Uno and version

will be the reference versions of Arduno, moving forward. The Uno is the latest in a series of USB Arduino boards, and the reference model for the Arduino platform; for a comparison with previous versions, see the <u>index of Arduino boards</u>.

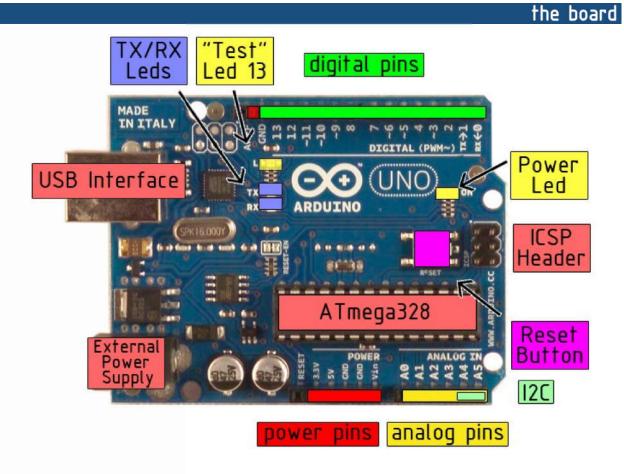


# Technical Specification

EAGLE files: arduino-duemilanove-uno-design.zip Schematic: arduino-uno-schematic.pdf

#### Summary

Microcontroller	ATmega328			
Operating Voltage	5V			
Input Voltage (recommended) 7-12V Input				
Voltage (limits)	6-20V			
Digital I/O Pins	14 (of which 6 provide PWM output)			
Analog Input Pins	6			
DC Current per I/O Pin	40 mA			
DC Current for 3.3V Pin	50 mA			
Flash Memory	32 KB of which 0.5 KB used by bootloader			
SRAM	2 KB			
EEPROM	1 KB			
Clock Speed	16 MHz			



#### Роwег

The Arduino Uno can be powered via the USB connection or with an external power supply. The power source is selected automatically.

External (non-USB) power can come either from an AC-to-DC adapter (wall-wart) or battery. The adapter can be connected by plugging a 2.1mm center-positive plug into the board's power jack. Leads from a battery can be inserted in the Gnd and Vin pin headers of the POWER connector.

The board can operate on an external supply of 6 to 20 volts. If supplied with less than 7V, however, the 5V pin may supply less than five volts and the board may be unstable. If using more than 12V, the voltage regulator may overheat and damage the board. The recommended range is 7 to 12 volts.

The power pins are as follows:

- VIN. The input voltage to the Arduino board when it's using an external power source (as opposed to 5 volts from the USB connection or other regulated power source). You can supply voltage through this pin, or, if supplying voltage via the power jack, access it through this pin.
- 5V. The regulated power supply used to power the microcontroller and other components on the board. This can come either from VIN via an on-board regulator, or be supplied by USB or another regulated 5V supply.
- 3V3. A 3.3 volt supply generated by the on-board regulator. Maximum current draw is 50 mA.
- **GND.** Ground pins.

Memory

The Atmega328 has 32 KB of flash memory for storing code (of which 0,5 KB is used for the bootloader); It has also 2 KB of SRAM and 1 KB of EEPROM (which can be read and written with the <u>EEPROM library</u>).

### Input and Output

Each of the 14 digital pins on the Uno can be used as an input or output, using <u>pinMode()</u>, <u>digitalWrite()</u>, and <u>digitalRead()</u> functions. They operate at 5 volts. Each pin can provide or receive a maximum of 40 mA and has an internal pull-up resistor (disconnected by default) of 20-50 kOhms. In addition, some pins have specialized functions:

- Serial: 0 (RX) and 1 (TX). Used to receive (RX) and transmit (TX) TTL serial data. TThese pins are connected to the corresponding pins of the ATmega8U2 USB-to-TTL Serial chip.
- External Interrupts: 2 and 3. These pins can be configured to trigger an interrupt on a low value, a rising or falling edge, or a change in value. See the <u>attachInterrupt()</u> function for details.
- **PWM: 3, 5, 6, 9, 10, and 11.** Provide 8-bit PWM output with the <u>analogWrite()</u> function.
- SPI: 10 (SS), 11 (MOSI), 12 (MISO), 13 (SCK). These pins support SPI communication, which, although provided by the underlying hardware, is not currently included in the Arduino language.
- LED: 13. There is a built-in LED connected to digital pin 13. When the pin is HIGH value, the LED is on, when the pin is LOW, it's off.



The Uno has 6 analog inputs, each of which provide 10 bits of resolution (i.e. 1024 different values). By default they measure from ground to 5 volts, though is it possible to change the upper end of their range using the AREF pin and the <u>analogReference()</u> function. Additionally, some pins have specialized functionality:

• I<sup>2</sup>C: 4 (SDA) and 5 (SCL). Support I<sup>2</sup>C (TWI) communication using the Wire library.

There are a couple of other pins on the board:

- AREF. Reference voltage for the analog inputs. Used with analogReference().
- **Reset.** Bring this line LOW to reset the microcontroller. Typically used to add a reset button to shields which block the one on the board.

See also the mapping between Arduino pins and Atmega328 ports.

#### Communication

The Arduino Uno has a number of facilities for communicating with a computer, another Arduino, or other microcontrollers. The ATmega328 provides UART TTL (5V) serial communication, which is available on digital pins 0 (RX) and 1 (TX). An ATmega8U2 on the board channels this serial communication over USB and appears as a virtual com port to software on the computer. The '8U2 firmware uses the standard USB COM drivers, and no external driver is needed. However, on Windows, an \*.inf file is required..

The Arduino software includes a serial monitor which allows simple textual data to be sent to and from the Arduino board. The RX and TX LEDs on the board will flash when data is being transmitted via the USB-to- serial chip and USB connection to the computer (but not for serial communication on pins 0 and 1).

A SoftwareSerial library allows for serial communication on any of the Uno's digital pins.

The ATmega328 also support I2C (TWI) and SPI communication. The Arduino software includes a Wire library to simplify use of the I2C bus; see the <u>documentation</u> for details. To use the SPI communication, please see the ATmega328 datasheet.

#### Programming

The Arduino Uno can be programmed with the Arduino software (<u>download</u>). Select "Arduino Uno w/ ATmega328" from the **Tools** > **Board** menu (according to the microcontroller on your board). For details, see the <u>reference</u> and <u>tutorials</u>.

The ATmega328 on the Arduino Uno comes preburned with a <u>bootloader</u> that allows you to upload new code to it without the use of an external hardware programmer. It communicates using the original STK500 protocol (<u>reference</u>, <u>C header files</u>).

You can also bypass the bootloader and program the microcontroller through the ICSP (In-Circuit Serial Programming) header; see these instructions for details.

## Automatic (Software) Reset

Rather than requiring a physical press of the reset button before an upload, the Arduino Uno is designed in a way that allows it to be reset by software running on a connected computer. One of the hardware flow control lines (DTR) of the ATmega8U2 is connected to the reset line of the ATmega328 via a 100 nanofarad capacitor. When this line is asserted (taken low), the reset line drops long enough to reset the chip. The Arduino software uses this capability to allow you to upload code by simply pressing the upload button in the Arduino environment. This means that the bootloader can have a shorter timeout, as the lowering of DTR can be well-coordinated with the start of the upload.

This setup has other implications. When the Uno is connected to either a computer running Mac OS X or Linux, it resets each time a connection is made to it from software (via USB). For the following half-second or so, the bootloader is running on the Uno. While it is programmed to ignore malformed data (i.e. anything besides an upload of new code), it will intercept the first few bytes of data sent to the board after a connection is opened. If a sketch running on the board receives one-time configuration or other data when it first starts, make sure that the software with which it communicates waits a second after opening the connection and before sending this data.

The Uno contains a trace that can be cut to disable the auto-reset. The pads on either side of the trace can be soldered together to reenable it. It's labeled "RESET-EN". You may also be able to disable the auto-reset by connecting a 110 ohm resistor from 5V to the reset line; see <u>this forum thread</u> for details.

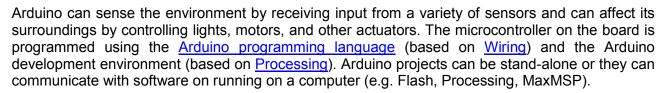
#### USB Overcurrent Protection

The Arduino Uno has a resettable polyfuse that protects your computer's USB ports from shorts and overcurrent. Although most computers provide their own internal protection, the fuse provides an extra layer of protection. If more than 500 mA is applied to the USB port, the fuse will automatically break the connection until the short or overload is removed.

Physical Characteristics



# How to use Arduino



Arduino is a cross-platoform program. You'll have to follow different instructions for your personal OS. Check on the Arduino site for the latest instructions. http://arduino.cc/en/Guide/HomePage



'indows Install



Once you have downloaded/unzipped the arduino IDE, you can Plug the Arduino to your PC via USB cable.



Now you're actually ready to "burn" your first program on the arduino board. To select "blink led", the physical translation of the well known programming "hello world", select

#### File>Sketchbook> Arduino-0017>Examples> **Digital>Blink**

Once you have your skecth you'll see something very close to the screenshot on the right.

In Tools>Board select

Now you have to go to **Tools>SerialPort** and select the right serial p

